

Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory		User Part Number PMEG045V100EPD Part Description												
										Nexperia DHAM	Schottky			
								Assembly reliability labs		SMD package				
Based on AEC-Q101 Test		Test Conditions	Duration	# Lots	# Quantity	# Rejects								
	TEST													
	Pre- and Post-Stress													
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below								
		JESD22-A113												
	PC	Bake Tamb = 125 °C	24 hours											
4 A 1	Preconditioning	Soak Tamb = 85 °C, RH = 85% Reflow soldering	168 hours 3 cycles	010	E0200	0								
# A1	Freconditioning		3 Cycles	810	58300	0								
	UTDD	MIL-STD-750-1 M1038 Method A												
	HTRB High Temperature Reverse	Tj = Tjmax, Vr = 100% of max. datasheet												
# B1	Bias	reverse voltage ^[1]	1000 hours	116	9280	0								
# DI	Dias	reverse voltage	1000 Hours	110	9280	U								
	тс	JESD22-A104												
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	170	13600	0								
,,,,,	. , , ,	IESD22-A102	1000 cycles	170	15000									
	AC	Tamb = 121 °C, RH = 100 %												
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)	96 hours	170	13600	0								
, 715 dic		· · ·	30 110015	17.0	15000									
	H3TRB	JESD22-A101												
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of												
# A2 alt	Temperature Reverse Bias	rated reverse voltage ^{[1], [2]}	1000 hours	170	13600	0								
		MIL-STD-750 Method 1037												
	IOL	ton = toff, devices powered to insure ΔTj =												
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	170	13600	0								
	RSH	JESD22-A111												
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	130	3900	0								
	SD													
# C10	Solderability	J-STD-002		363	3630	0								

^[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	9280	0	0.46	2.19E+09

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^[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.